SPECIFICATIONS

Product No. : **X1G003821002300**

MODEL : **TG-5021CE-21N**

SPEC. No. :

DATE: **Aug. 10. 2012**

SEIKO EPSON CORPORATION

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SPECIFICATIONS

1. Application

This document is applicable to the temperature compensated crystal oscillator (TCXO) that is delivered from SEIKO EPSON Corp.

This product is compliant with RoHS Directive.

This Product supplied (and any technical information furnished, if any) by SEIKO EPSON Corporation shall not be used for the development and manufacture of weapon of mass destruction or for other military purposes. Making available such products and technology to any third party who may use such products or technologies for the said purposes are also prohibited.

This product listed here is designed as components or parts for electronics equipment in general consumer use. We do not expect that any of these products would be incorporated or otherwise used as a component or part for the equipment, which requires an extra high reliability, such as satellite, rocket and other space systems, and medical equipment, the functional purpose of which is to keep life.

2. Model / Product No.

The model is TG-5021CE-21N / X1G003821002300

3 Amendment and abolishment

Amendment and/or abolishment of this specification are subject to the agreement of both parties.

4 Contents

[1] Characteristics

- Reflowable and high density mounting type ultra small size SMD (3.2×2.5×0.9 mm).
- Using the heat-resisting type AT cut quartz crystal
  allows almost the same temperature soldering as universal SMD IC.
- Operating supply voltage : 3.0 V.

[2] Absolute maximum ratings

Parameter	Symbol	Min.	Max.	Unit	Condition
Supply voltage	$_{CC}$-GND	-0.3	4.5	V	
Storage temperature range	T_stg	-40	+85	°C	

[3] Operating range

Item		Symbol	Min.	Typ.	Max.	Unit	Condition
Supply voltage		V_{CC}	2.7	3.00	3.30	V	V_{CC}=3.00V ± 10%
Operating temperature range		T_use	-40	+25	+ 85	°C	
Output load		Load_R	9	10	11	KΩ	C_L // R_L
		Load_C	9	10	11	pF	
	DC-cut capacitor	Cc	0.01			μF	

DC-cut capacitor is not included in our TCXO. Please insert DC-cut capacitor in output line

4.Frequency characteristics

1) Output frequency 26.000000 MHz

2) Frequency characteristics (V_{CC}=3.0V, Load 10 kΩ//10 pF(DC cut), T_use = +25 °C)

Parameter	Symbol	Value	Unit	Note
Frequency tolerance .	f_tol(OSC)	+/- 1.5×10^{-6} Max.	-	T_use =+25 °C +/-2 °C Reflow cycles : 2 times.*1
Frequency / temperature Characteristics	fo-Tc	+/- 2.5×10^{-6} Max.	-	T_use =-40 °C to +85 °C Based on frequency at +25 °C
Frequency / Load coefficient	fo-Load	+/- 0.2×10^{-6} Max.	-	Load :10 kΩ//10 pF +/-10 % each
Frequency / voltage coefficient	fo-Vcc	+/- 0.2×10^{-6} Max.	-	VCC=3.0V +/- 10%
Frequency ageing	f_age	+/- 1.0×10^{-6} Max.	-	T_use =+25 °C 1 year

*1 Measurement of frequency deviation is made 1h after reflow soldering.

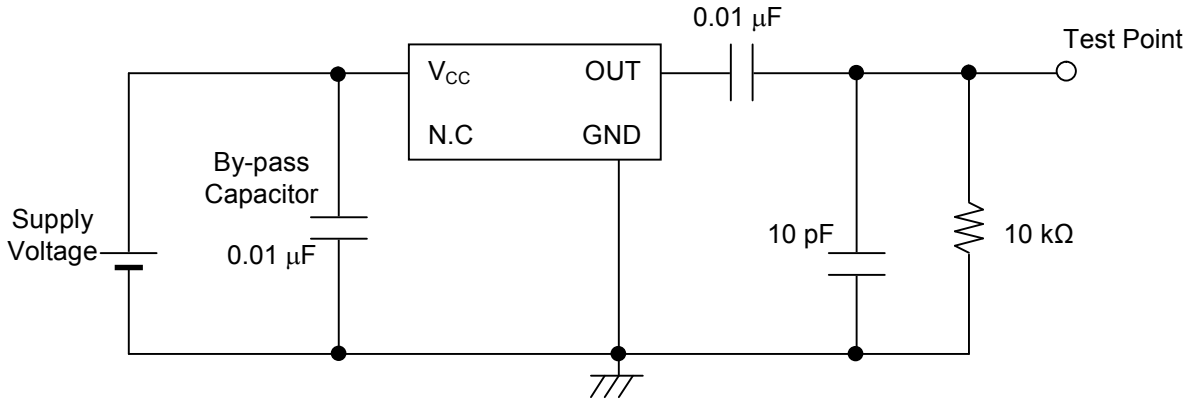
4.Electrical characteristics

(V_{CC}=3.0 V, Load 10 kΩ//10 pF(DC cut), T_use = +25 °C)

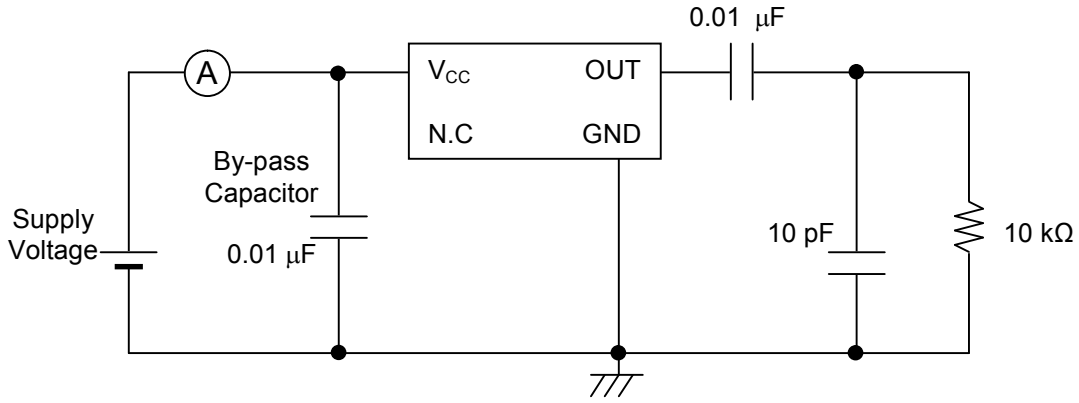
Parameter	Symbol	Value			Unit	Note
		Min.	Typ.	Max.		
Current consumption	Icc			2.0	mA	
Output level	Vpp	0.8	1.2		V	Peak to peak voltage
SSB Phase noise	L(f)			-140	dBc/Hz	Offset:10kHz

[6] Test circuit

1) Output Load : 10 kΩ//10 pF



2) Current consumption



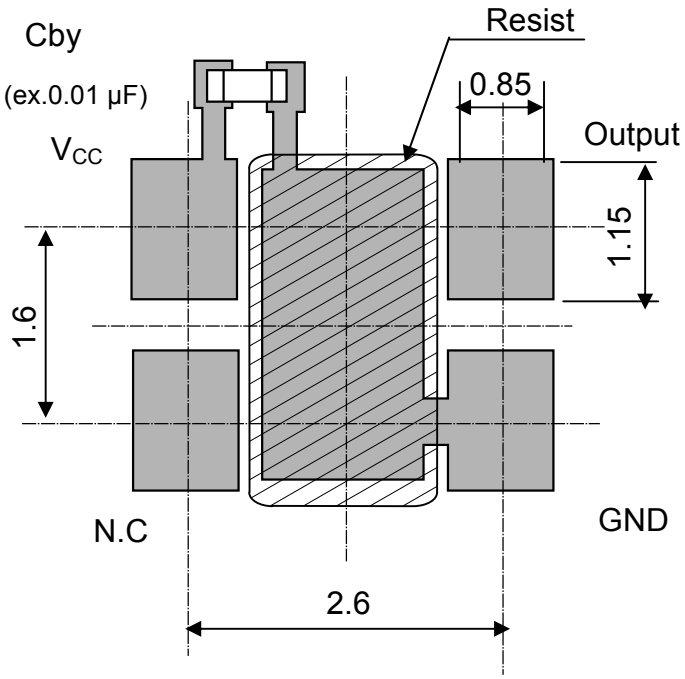
3) Conditions

1. Oscilloscope : Impedance Min. 1 MΩ
   Input capacitance Max. 10 pF
   Band width Min. 300 MHz

Impossible to measure both frequency and wave form at the same time.(In case of using oscilloscope's amplifier output, possible to measure both at the same time.)

2. Load_C includes probe capacitance.
3. A capacitor (By-pass:0.01 μF) is placed between V_{CC} and GND,and closely to TCXO.
4. Use the current meter whose internal impedance value is small.
5. Power Supply
   Impedance of power supply should be as lowest as possible.
6. GND should apply one point earth.

[7] Recommendation Foot pattern



※ Please connect Cby(bypass capacitor) quite near by ”Vcc” terminal.

※ It is desirable to draw GND pattern under TCXO.

[8] Environmental and mechanical characteristics

(The company evaluation condition. we evaluate it by the following examination item and examination condition.)

No.	Item	Value *1		Test method
		Freq. Tolerance [1×10^{-6}] *2	Electrical characteristics	
1	High temp. storage *3	± 2.0	Satisfy Output level after test	+85 °C × 1 000 h
2	Low temp. storage *3	± 2.0		-40 °C × 1 000 h
3	Temp. cycle *3	± 2.0		-40 °C to +85 °C (30 min × 1 000 cycle/each)
4	Resistance to Soldering heat (Reflow characteristics)	± 1.0		Reflow furnace with the condition 3 times
5	Drop	± 2.0		Free drop from 1.5 m height on a concrete floor for 3 times.
6	Vibration (variable frequency)	± 1.0		10 Hz to 55 Hz 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s^2 10 Hz → 500 Hz → 10 Hz 15 min./cycle 6 h(2 h × 3 directions)
7	Solderability	Terminals must be 95 % covered with fresh solder		Dip termination into solder bath at +235 °C for 5 s (Using Rosin Flux)

Notes

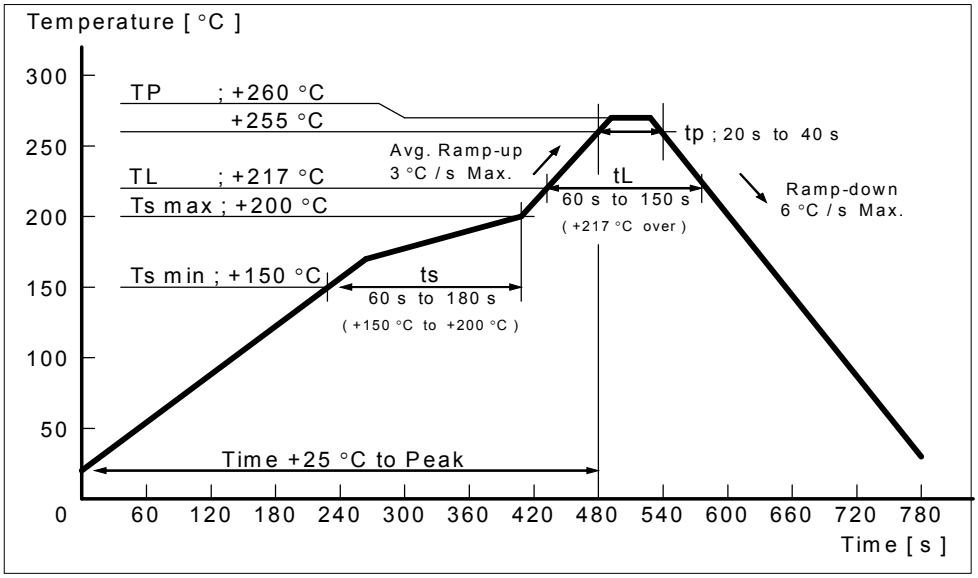
1.*1 each test is independent.

2.*2 measuring 2 h to 24 h later leaving in room temperature after each test.

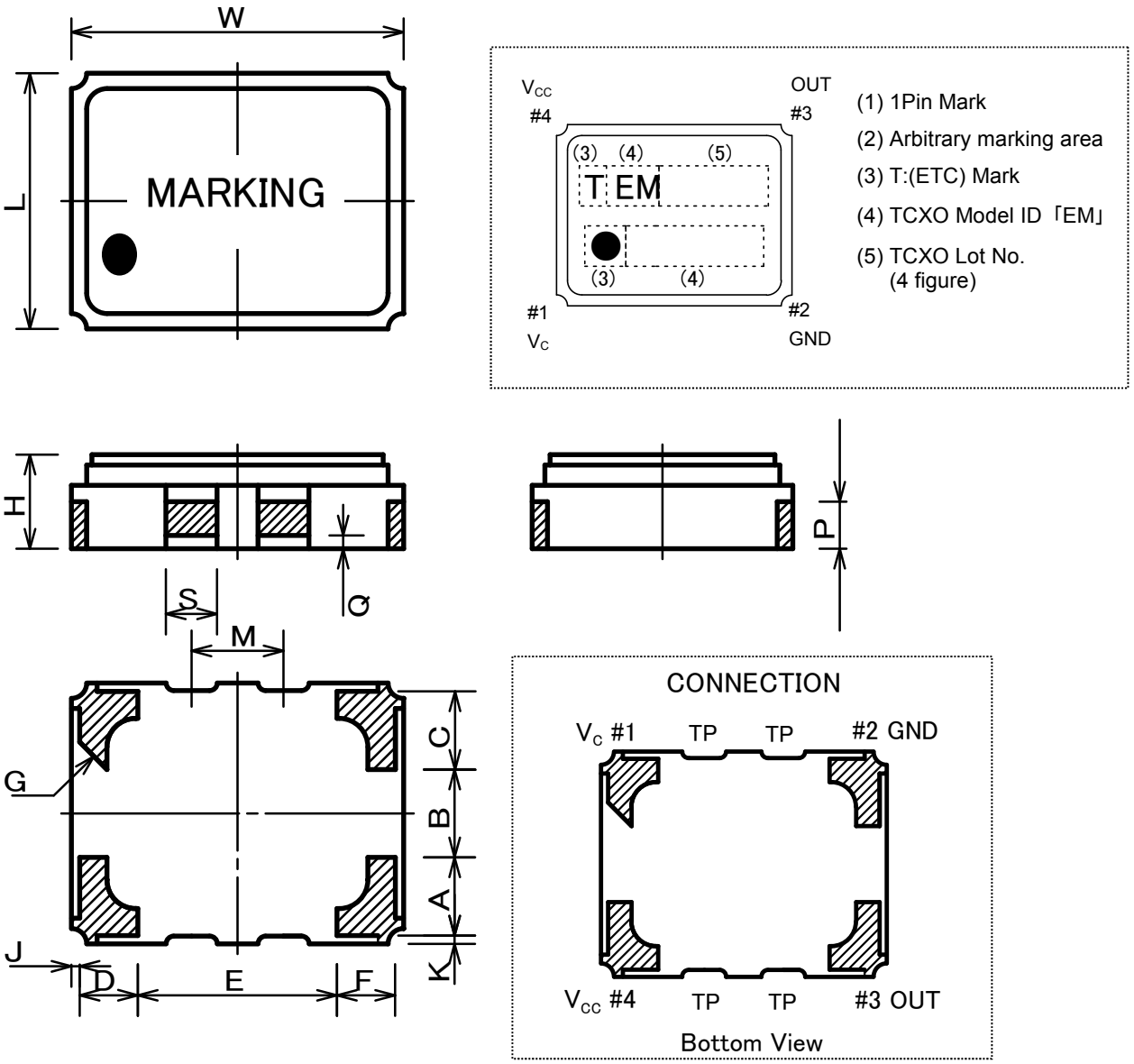
3.*3 Pre conditionings

Initial value shall be reflow 2 times and after 24 h at room temperature.

• REFLOW SOLDERING PROFILE (Reference to JEDEC J-STD-020C)



[9] OUTLINE DRAWING



(unit : mm)

Dim.	Min.	Typ.	Max.	Dim.	Min.	Typ.	Max.
W	3.05	3.20	3.35	F	—	0.57	—
L	2.35	2.50	2.65	G	—	C 0.27	—
H	0.80	0.90	1.00	J	—	0.08	—
A	—	0.765	—	K	—	0.08	—
B	0.76	0.86	0.96	M	0.80	0.90	1.00
C	—	0.765	—	P	0.41	0.46	0.51
D	—	0.57	—	Q	—	0.13	—
E	1.85	1.95	2.05	S	0.40	0.50	0.60

Material
Base : Ceramics
Terminal : W-Ni-Au
Lid : Fe-Ni-Co

[10] Attention

Prior to using this product, please carefully read the section entitled “Precautions” on our Web site (http://www.epsontoyocom.co.jp/english/support/support.html) for instructions on how to handle and use the product properly to ensure optimal performance of the product in your equipment. Before using the product under any conditions other than those specified therein, please consult with us to verify and confirm that the performance of the product will not be negatively affected by use under such conditions.

In addition to the foregoing precautions, in order to avoid the deteriorating performance of the product, we strongly recommend that you DO NOT use the product under ANY of the following conditions:

(1) Mounting the product on a board using water-soluble solder flux and using the product without removing the residue of the flux completely from the board. The residue of such flux that is soluble in water or water-soluble cleaning agent, especially the residues which contains active halogens, will negatively affect the performance and reliability of the product.
(2) Using the product in any manner that will result in any shock or impact to the product.
(3) Using the product in places where the product is exposed to water, chemicals, organic solvent, sunlight, dust, corrosive gasses, or other materials.
(4) Using the product in places where the product is exposed to static electricity or electromagnetic waves.
(5) Applying ultrasonic cleaning without advance verification and confirmation that the product will not be affected by such a cleaning process, because it may damage the crystal, IC and/or metal line of the product.
(6) Touching the IC surface with tweezers or other hard materials directly.
(7) Using the product under any other conditions that may negatively affect the performance and/or reliability of the product.
(8) Using the product with power line ripple exceeding 200 mV(p-p) level.

Should any customer use the product in any manner contrary to the precautions and/or advice herein, such use shall be done at the customer’s own risk.

登録 REGIST.	
版	年月日 DATE
1	07.02.07
2	10.05.10
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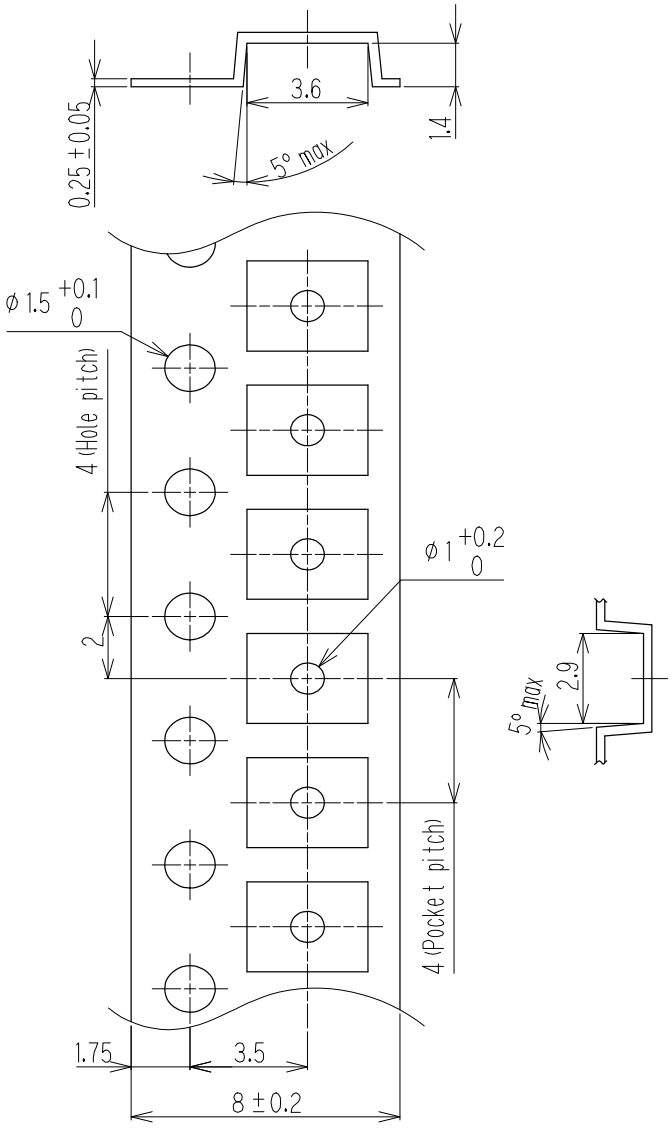
Packing Specification		名称 TITLE	仕番 SPEC. NO.
		Packing Standard ③	TN4-24998
作成部門 SECTION 49833	作成年月日 DATE '07.02.07	MODEL TCO-587x・TCO-586x・TG-50xxCE	頁 P. 1 / 6

1. TAPE & REEL PACKAGING SPECIFICATION

1.1. Embossed tape dimension & Outline drawings



[Size in mm]

※ The radius of each corner is 0.3mm max.

※ 10 feeding hole pitches cumulative tolerance on tape is ±0.2mm max.

※ The material is polystyrene.

※ Tolerance for all measurements are ±0.1mm unless otherwise stated.

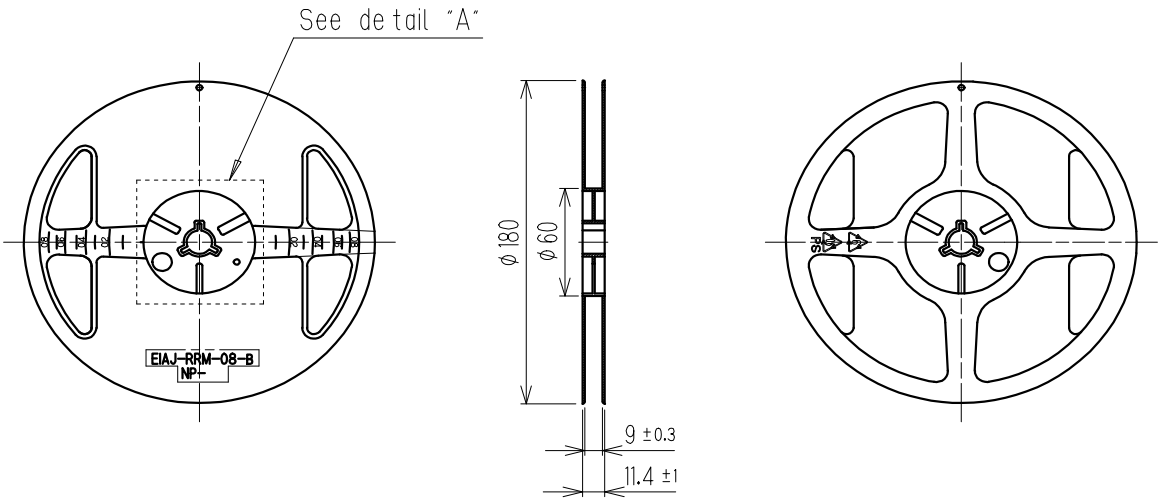
承認 APP.	照査 CHK'D	照査 CHK'D	作成 DRAW
H.TAKANASHI	H.KANNO		A.KAKUMAE

改版記事 DESCRIPTION

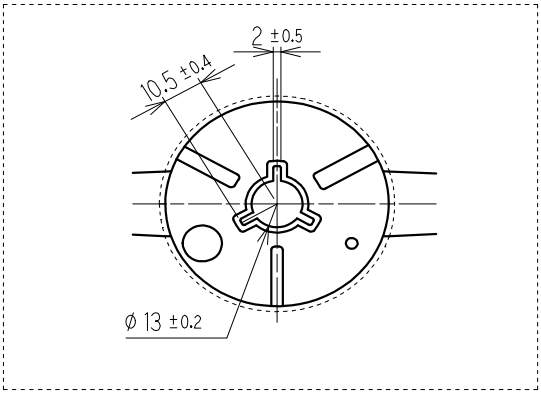
② '10.05.10 Draw N.Y App Y.S
1.4 Marking
Changed reel label

③ '11.04.22 Draw N.Y App Y.S
Title Changed
TG-5005CE ⇒ TG-50xxCE

1.2. Reel dimension & Outline drawing



Detail "A"



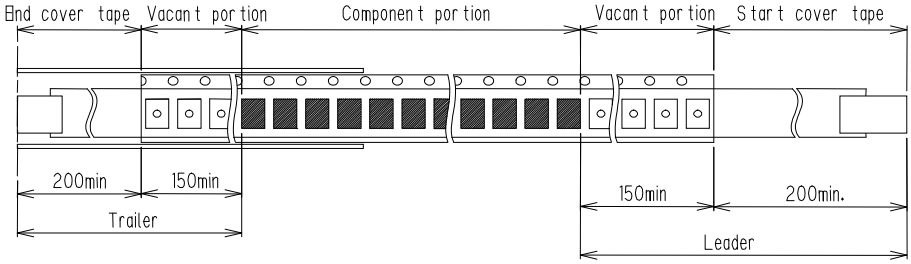
Material

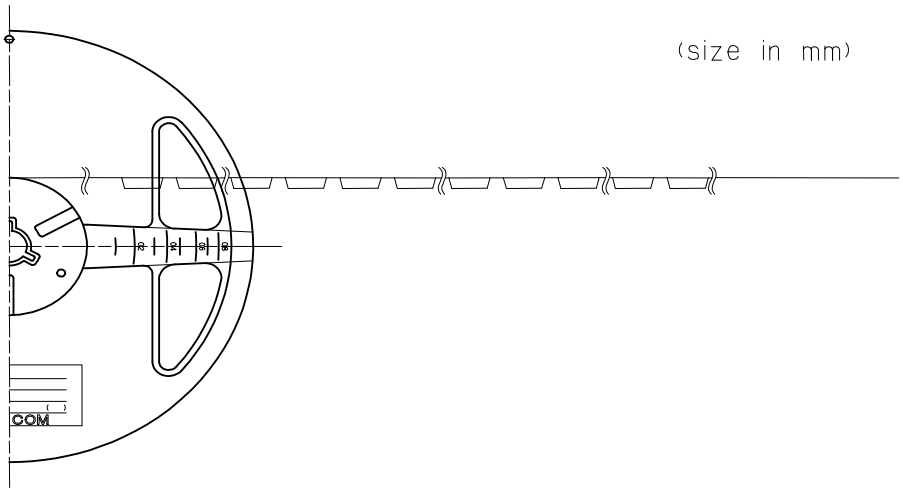
PS(REEL)

[Size in mm]

※ Tolerance for all measurements are +/-0.1mm unless otherwise stated.

1.3. Taping package





※ Direction of taking up reel is clock-wise as above. There are sprocket holes on the right hand side of the tape when it is pulled out as shown above.

※ The end of leader is fixed on the tape with adhesive tape as shown above.

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1.4. Marking

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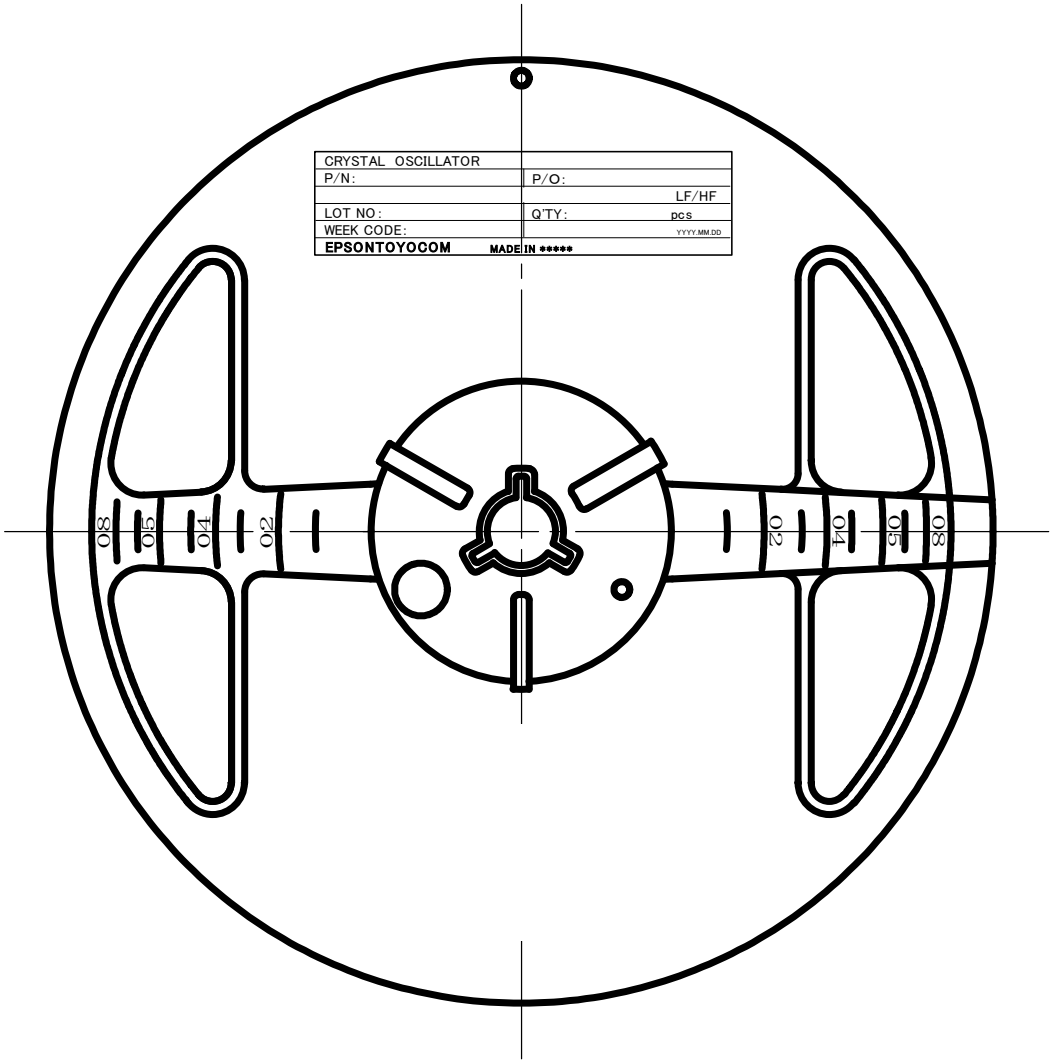
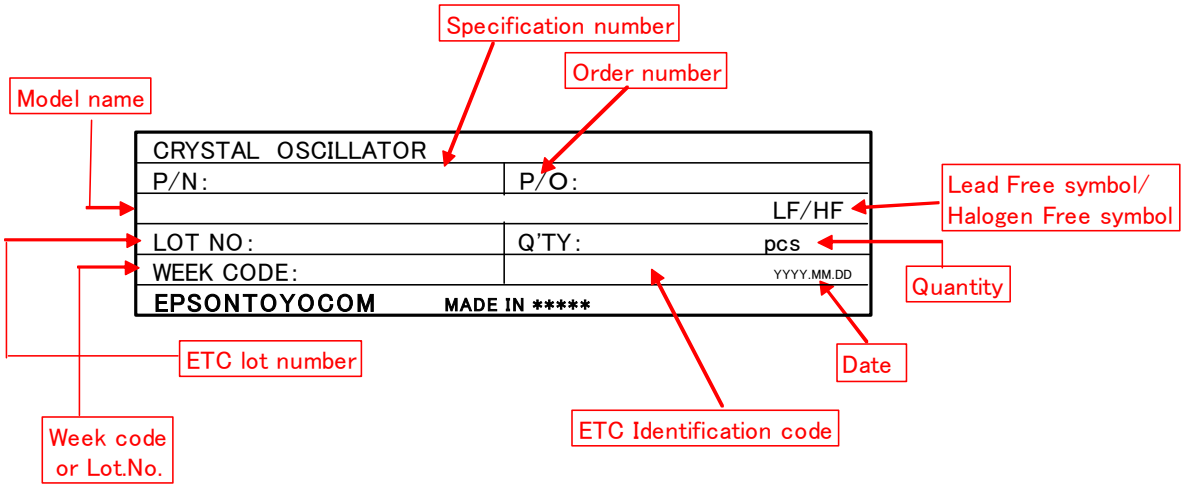


Marking Label



承認 APP.	照査 CHK'D	照査 CHK'D	作成 DRAW
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1.5. Cover tape peeling-off strength

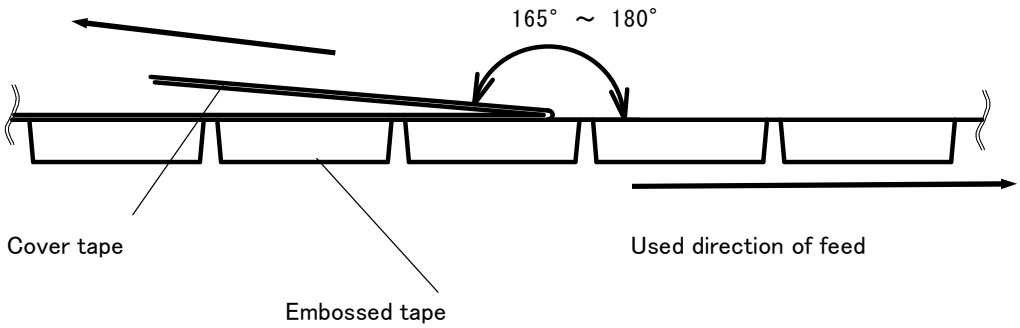
※ Angle :165° ～180° from feeding direction

※ Speed :5mm/sec.

※ Force :0.2N～0.7N

※ Others :There shall be no split or breakage of the carrier tape and the cover tape when peeling away the fixing tape.

Pulling direction of cover tape

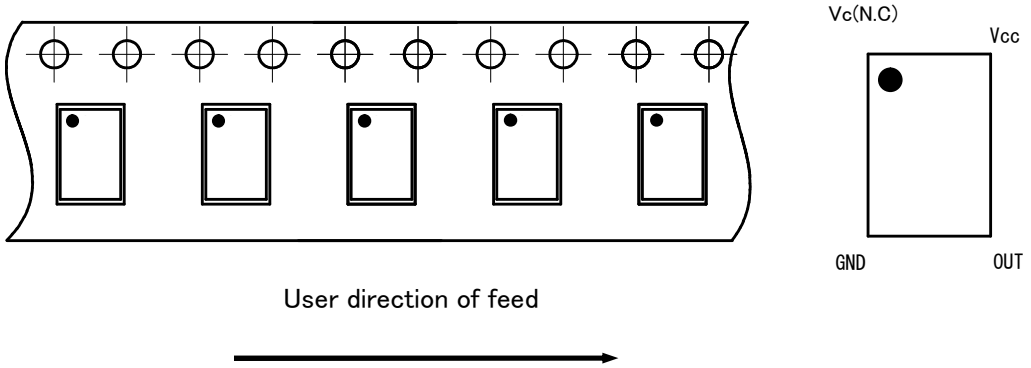


1.6. Quantity of components

2000pcs／reel(MAX.)
500pcs／reel(MIN.)

※ The above quantity is our standard packing size.
In case of an odd sum as per the purchased quantity, the packing quantity might be below our standard minimum packing size.

1.7. Oscillator orientation : TOP VIEW



承認 APP.	照査 CHK'D	照査 CHK'D	作成 DRAW
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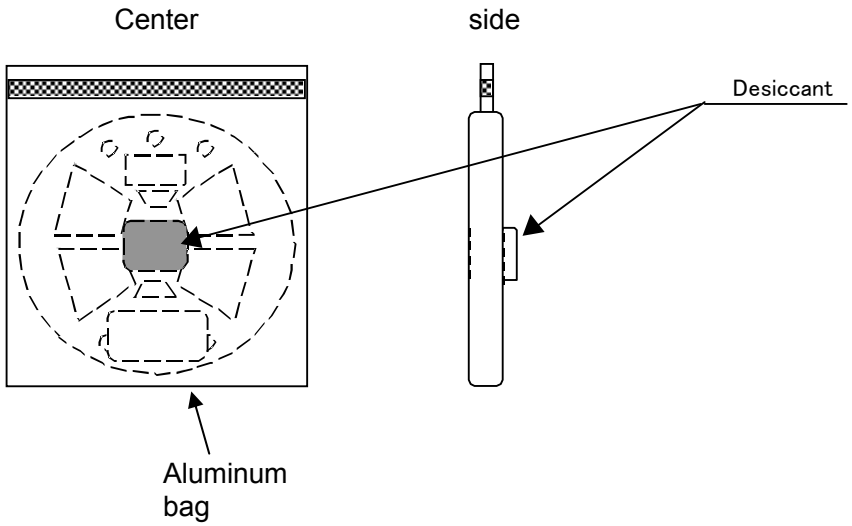
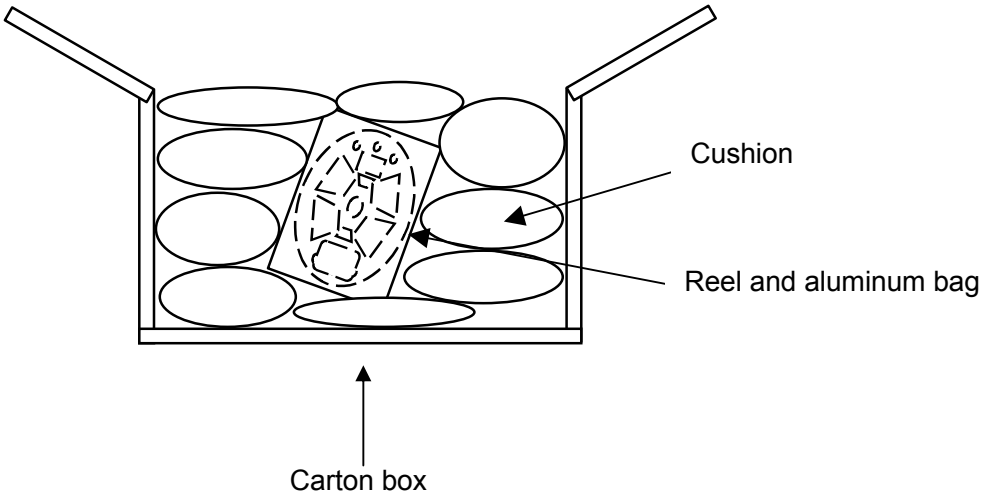
EPSON TOYOCOM CORPORATION エプソントヨコム株式会社

1.8. .Packaging

Reel is in aluminum bag. (vacuum-packed)



This reel is in carton box with cushion.



承認 APP.	照査 CHK'D	照査 CHK'D	作成 DRAW
H.TAKANASHI	H.KANNO		A.KAKUMAE

改版記事 DESCRIPTION

登録 REGIST		Flow chart	Process	Control item	Check item	Inspection item	Operation						Disposal of defected parts		Remarks
版	年月日 DATE						Procedure	Operator	Lot	Sampling rate	Equipment	Record	In process	Defected parts	
1	11.04.22	IC **Electrical and Mechanical parts**													
2		I	Incoming inspection			Part name	inspection procedure	Quality assurance div.	Delivered lot	100%	Visual	Incoming inspection record	—	Return to vender/ Issue a Notice of defective	
3						Quantity									
4		II	IC appearance inspection			Appearance of IC wafer	IC-001	Producion div.	Wafer	N=10chip	Microscope ×40	Travel sheet	—	Return to vender/ Issue a Notice of defective	
5		1	Bump bonding	Number of tool shots			IC-002	Producion div.	Wafer	100%	Built-in counter	Tool change check	changed capillary	Isolation the Product/ Issue a Notice of defective	
6					Stage temperature					Daily	Thermometer	Daily check sheet	Production halt/ Process investigation		
7		III	Test of bump shear strength			Bump dimension	IC-002	Producion div.	Wafer	N=4bump at changed capillary	Measuring Microscope	Travel sheet	Process investigation	Isolation the Product/ Issue a Notice of defective	
8						Shear strength					Bond tester	Xber-R Chart			
9		2	To paste Tape on IC wafer		Number of cutter shots		IC-003	Producion div.	Wafer	Daily	Built-in counter	Daily check sheet	Change cutter/ Work guidance	—	
10		3	Dicing	Abrasion loss of Blade			IC-004	Producion div.	Wafer	Wafer	Built-in measure	Tool change check	Change blade	Isolation the Product/ Issue a Notice of defective	
11					Resistivity of cutting water					Daily	Built-in measure	Travel sheet	Production halt/ Process investigation		
12		4	To clean IC wafer		Resistivity of cleaning water		IC-006	Producion div.	Wafer	Daily	Built-in measure	Daily check sheet	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
13		IV	Appearance inspection			Bonding condition	IC-002	Producion div.	Wafer	N=10chip	Microscope ×40	Travel sheet	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
14						Dicing condition	IC-004								
15		5	UV irradiation		UV intensity		IC-007	Producion div.	Wafer	Daily	UV radiometer	Daily check sheet	Change Metal halide lamp	Isolation the Product/ Issue a Notice of defective	
16		Crystal unit	Blow & Vacuum		Blow,Vacuum motion		IC-010	Producion div.	Product lot	Daily	Visual	Daily check sheet	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
		6	Plasma etching		Flow of Argon		IC-011	Producion div.	Product lot	Daily	Built-in flowmeter	Daily check sheet	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
		7			Flow of oxygen										
		8	Flip chip bonding	Number of tool shots			IC-016	Producion div.	Product lot	100%	Built-in counter	Tool change check	Clean the bonding too	Isolation the Product/ Issue a Notice of defective	
					Stage temperature					Daily	Thermometer	Daily check sheet	Production halt/ Process investigation		
						Bonding impedance				100%	Built-in measure	Travel sheet	(Process investigation	Scrap	
		V	Inspection of die share strength			Bump dimension	IC-016	Producion div.	Product lot	N=6bump	Measuring Microscope	Travel sheet	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
						Shear strength				N=2pcs	Bond tester	Xber-R Chart			
		VI	Appearance inspection			Flipchip bonding condition	IC-016	Producion div.	Product lot	N=2pcs	Microscope ×15	Travel sheet	Process investigation /Alignment	Scrap	
		9	Under fill filling	Chip coat storage temperature			IC-020	Producion div.	Product lot	Daily	Thermometer	Daily check sheet	Scrap the resin	—	
				Pot life time						100%	Built-in measure	Tool change check	Change resin	Isolation the Product/ Issue a Notice of defective	
					Stage temperature					Daily	Thermometer	Daily check sheet	Production halt/ Process investigation		
		10	Curing	Curing time			IC-022	Producion div.	Product lot	Product lot	Timer	Travel sheet	Work guidance	Scrap	
					Chamber temperature					Daily	Thermometer	Daily check sheet	Production halt/ Process investigation		
		VII	Appearance inspection			Under fill condition	IC-020	Producion div.	Product lot	100%	Microscope ×15	Travel sheet	Process investigation	Scrap	
						Defective rate				100%	PC	P Chart		Issue a Notice of defective	

承認 APP.	照査 CHK'D	作成 DRAW	改版記事 DESCRIPTION	TiTle	QC Process Chart of TG-5021CE Series			
				Date	22nd. Apr. 2011	Document No.	TG5021CE-00-AFE	1/2

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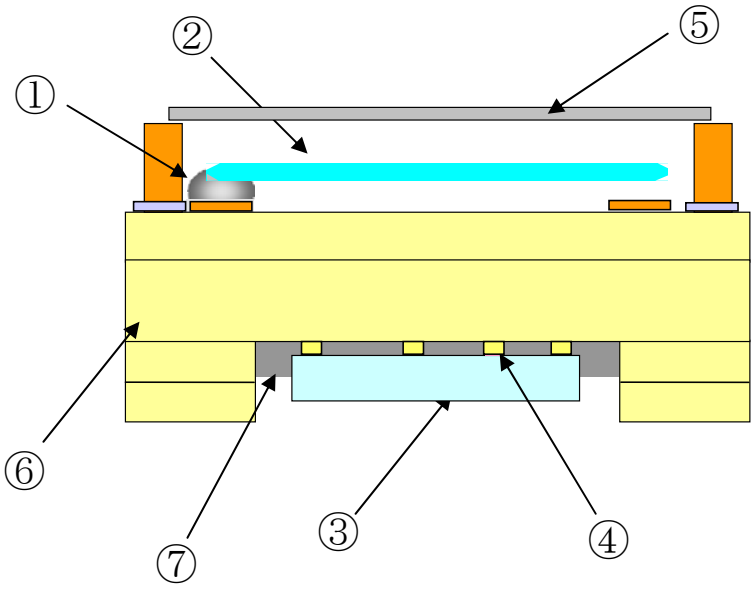
Flow chart	Process	Control item	Check item	Inspection item	Operation						Disposal of defected parts		Remarks
					Procedure	Operator	Lot	Sampling rate	Equipment	Record	In process	Defected parts	
11	Reflow		Temperature profile		IC-031	Producion div.	Product lot	Daily	Thermometer	Daily check sheet	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
Ⅷ	Frequency inspection at high temperature		Stage temperature		IC-032	Producion div.	Product lot	Daily	Thermometer	Daily check sheet	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
				Frequency at high temperature				N=306pcs	Frequency counter	Tool change check sheet	Process investigation		
Ⅸ	Temperature characteristics adjustmet and inspection		Stage temperature		IC-054	Producion div.	Product lot	Daily	Thermometer	Daily check sheet	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
				Temperature characteristics				100%	Temperature characteristic measurement	Travel sheet	(Process investigation	Re-work	
				Defective rate				Product lot	PC	P Chart	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
Ⅹ	Final inspection			Dimension	IC-045	Quality assurance div.	Product lot	N=3pcs	Calipers	Inspection record Travel sheet	Process investigation	Return to Production div./ Issue a Notice of defective	
				Appearance				AQL 1.0%	Amplifier				
				Part name, Quantity				N=3pcs	Amplifier				
				Frequency tolerance				AQL 0.4%	Frequency counter				
				DC supply current				AQL 0.4%	Multimeter				
				Temperature characteristics				AQL 0.4%	Inspection record				
Ⅺ	electrical characteristics inspection			Frequency tolerance	IC-043	Producion div.	Product lot	100%	Frequency counter	Travel sheet	Process investigation	Issue a Notice of defective	
				RF output					Oscilloscope				
				Duty cycle									
				DC supply current					Multimeter				
				Frequency control range					Frequency counter				
				Circuit frequency stabilityvs. supply voltage									
12	Marking			Marking contents	IC-043	Producion div.	Product lot	Product lot	Built-in word recongnition system	Travel sheet	Production halt/ Process investigation	Isolation the Product/ Issue a Notice of defective	
13	Taping		Peeling strength		IC-043	Producion div.	Packing lot	Daily	Peeling tester	Daily check sheet	Process investigation /Adjust the heater	Isolation the Product/ Issue a Notice of defective	
Ⅻ	Taping inspection			Direction	IC-043	Quality assurance div.	Packing lot	N=3pcs	Amplifier	Inspection record	Production halt/ Process investigation	Return to Production div./ Issue a Notice of defective	
				Marking contents									
	Packing and shipping			Quantity	Packing Instruction	Production control div.	Shipping lot	100%	Visual	Shipping record	—	Return to Production div.	

改版記事 DESCRIPTION

TiTle	QC Process Chart of TG-5021CE Series			
Date	22nd. Apr. 2011	Document No.	TG5021CE-00-AFE	2/2

TG-5021CE　Structure

Section



material Table		
material		Specification
①	Adhesives	Adhesives
②	XTAL blank	ATCut
③	IC	CMOS
④	FC bump	Au bump wire
⑤	Lid	Kovar
⑥	PKG	Ceramic
⑦	UF	Potting resin

T-1004-01-01		
MGR.	CHK.	ENG.
Y.Shishido	T.Matsuda	N.Yoshida

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RELIABILITY TEST DATA

Product Name : TG-5021CE series

The Company evaluation condition
We evaluate it by the following examination item and examination condition. No. TCE11-CO-001-1E

No.	ITEM	TEST CONDITIONS	Value *1		TEST Qty	FAIL Qty
			Freq. Tolerance D f / f *2 [1×10^{-6}]	Electrical characteristics	[n]	[n]
1	High temp. storage	+85±2℃ × 1000h *3	± 2.0	Satisfy Output level after test	20	0
2	Low temp. storage	-40±2℃ × 1000h *3	± 2.0		20	0
3	Temperature cycle	-40⇔+85℃ (30 min at each temp.1000 cycles) *3	± 2.0		20	0
4	Resistance to soldering heat	Reflow furnace with the condition 3 times	± 1.0		20	0
5	Drop Test	Free drop from 1.5 m height on a for 3 times.(against concrete floor)	± 2.0		20	0
6	Vibration	10 Hz to 55 Hz 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s2 10 Hz → 500 Hz → 10 Hz 15 min./cycle 6 h(2 h × 3 directions) *3	± 1.0		20	0
7	Solderability	Dip termination into solder bath at +235℃ for 5s(Using Rosin Flux)	Terminals must be 95% covered with fresh solder		20	0

Notes
1. *1 Each test done independently.
2. *2 Measuring 2 h to 24 h later leaving in room temperature after each test.
3. *3 Initial value shall be measured after 24 h storage at room temperature after pre-conditioning .
   Pre-conditioning: Reflow (3 time)

Production Engineering Department

signature T. Shishido

Qualification Data

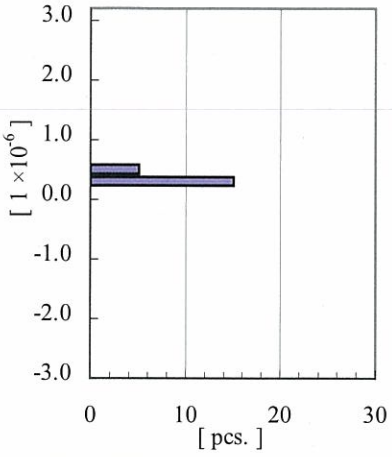
EPSON TOYOCOM

Product Name : TG-5021CE series

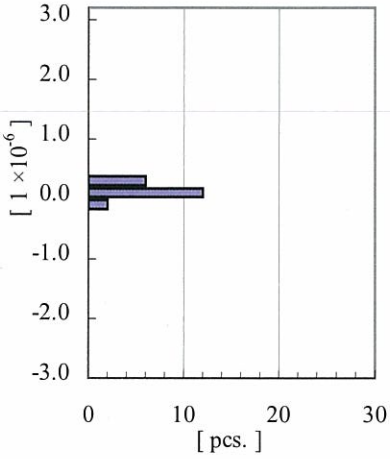
Δ f / f

No. TCE11-CO-001-1E

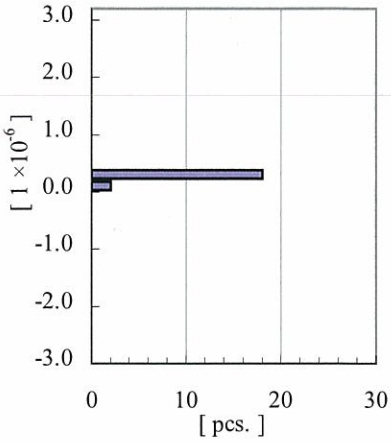
1. High temp. storage
+85℃ × 1 000 h



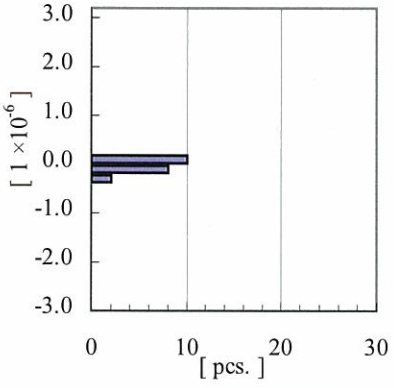
2. Low temp. storage
-40 ℃ × 1 000 h



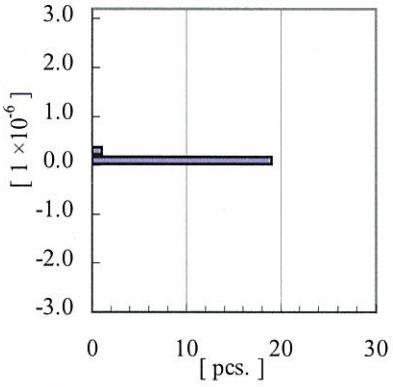
3. Temp. cycle
-40 ℃ ⇔ +85 ℃ 100 cycles



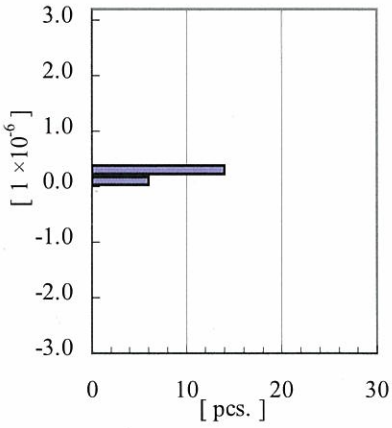
4. Resistance to soldering heat
For convention reflow soldering furnace (3 times)



5. Vibration
10 Hz to 55 Hz amplitude 0.75 mm
55 Hz to 500 Hz acceleration 98 m/s^2
15 min / cycle
6 h (2 h × 3 directions)



6. Shock
150g jig 1.5m height × 6 directions 3 times



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